## LNJ318C8TRA

### Surface Mounting Chip LED

Dome-Lens Type

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol Rating		Unit	
Power dissipation	$P_{\mathrm{D}}$	60	mW	
Forward current	$I_{\mathrm{F}}$	20	mA	
Pulse forward current *	$I_{FP}$	60	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

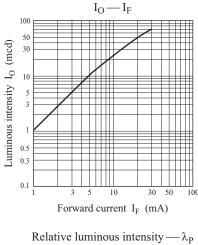
#### ■ Lighting Color

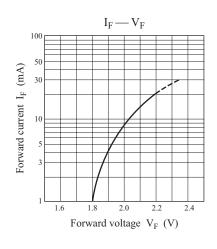
• Yellow Green

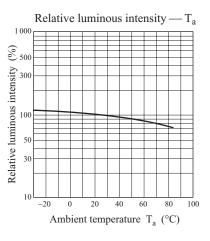
#### ■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

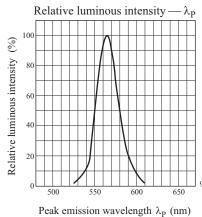
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	I <sub>O</sub>	$I_F = 10 \text{ mA}$	10	25		mcd
Reverse current	$I_R$	$V_R = 4 V$			10	μΑ
Forward voltage	$V_{\mathrm{F}}$	$I_F = 10 \text{ mA}$		2.03	2.60	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		565		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		30		nm

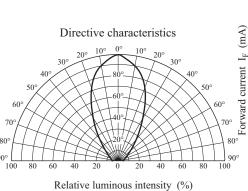
Note) \*: Measurement tolerance: ±20%

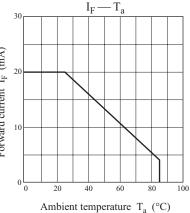






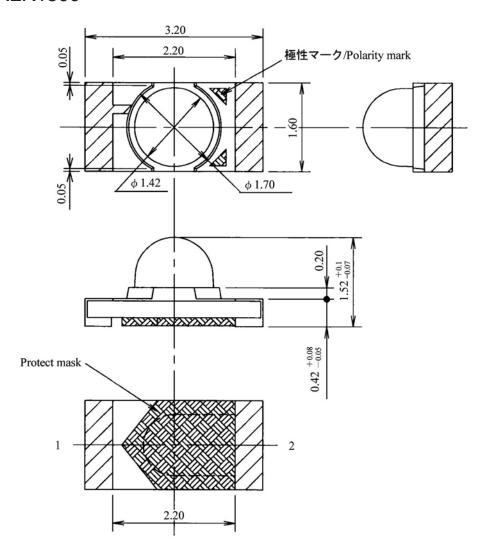






### ■ Package (Unit: mm)

## KLTLTN2K1800



• Pin name

2

- 1: Anode
- 2: Cathode

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